

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM375327

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
Silicon Valley Bank		03/02/2016	CORPORATION: CALIFORNIA
RECEIVING PARTY DATA			
Name:	Anadigics, Inc.		
Street Address:	141 Mount Bethel Road		
City:	Warren		
State/Country:	NEW JERSEY		
Postal Code:	07059		
Entity Type:	CORPORATION: DELAWARE		
PROPERTY NUMBERS Total: 1			
Property Type	Number	Word Mark	
Registration Number:	2896625	ANADIGICS	
CORRESPONDENCE DATA			
Fax Number:	7324762524		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	7324762524		
Email:	pPhillips@greenbaumlaw.com		
Correspondent Name:	Peter B Phillips, Esq.		
Address Line 1:	99 Wood Ave. South		
Address Line 2:	4th Fl.		
Address Line 4:	Iselin, NEW JERSEY 08830		
ATTORNEY DOCKET NUMBER:	25309-004		
NAME OF SUBMITTER:	Peter B. Phillips, Esq.		
SIGNATURE:	/Peter B. Phillips, Esq./		
DATE SIGNED:	03/02/2016		
Total Attachments: 12			
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TERMINATION OF SECURITY INTEREST

This Termination of Security Interest dated March 1, 2016 is by Silicon Valley Bank, a California corporation having a loan production office at 275 Grove Street, Suite 2-200, Newton, Massachusetts 02466 (the "Bank"), in favor of ANADIGICS, Inc., a Delaware corporation having its principal place of business located at 141 Mount Bethel Road, Warren, New Jersey 07059 ("Anadigics").

WHEREAS, Anadigics was indebted to the Bank under a Loan and Security Agreement dated October 24, 2014 (the "Loan Agreement") and in connection therewith granted a security interest in the patents more particularly described and incorporated in this document by reference and attached hereto as Schedule A (the "Patents"), the trademarks more particularly described and incorporated in this document by reference and attached hereto as Schedule B (the "Trademarks"), and the copyrights more particularly described and incorporated in this document by reference and attached hereto as Schedule C (the "Copyrights");

NOW THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, the Bank does hereby release and discharge the security interest in the Patents shown in Schedule A, the Trademarks shown in Schedule B, and the Copyrights shown in Schedule C granted to it by Anadigics, the debt secured thereby having been paid and satisfied in full.

IN WITNESS WHEREOF, the parties hereto have caused this Termination of Security Interest to be duly executed by their respective officers thereunto duly authorized as of the date first above written.

SILICON VALLEY BANK

By Michael Quinn
Michael Quinn
VP

STATE OF MA)
COUNTY OF Middlesex)

SS:

On this 1 day of March, 2016, before me personally appeared Michael Quinn, to me known, who, being by me duly sworn, did depose and say that he is the Vice President of Silicon Valley Bank, the corporation described in and which executed the foregoing instrument; and that he signed his name thereto on behalf of the corporation as his free act and deed.



Shannon Hinkley

SCHEDULE A

PATENTS

U.S. ISSUED PATENTS		
TITLE	PAT. NO.	ISSUE DATE
Protection circuit for an electronic circuit	8,767,361	7/1/2014
Protection circuit	8,743,518	6/3/2014
RF directional coupled output from a quadrature combined amplifier	8,737,520	5/27/2014
Reconfigurable output matching network for multi band RF power amplifier	8,736,378	5/27/2014
Multistage amplification and high dynamic range rectification circuit	8,724,355	5/13/2014
Vector voltage samplers for RF interface control of power amplifier	8,717,104	5/6/2014
Current mirror circuit	8,717,092	5/6/2014
Low leakage logic circuit	8,680,885	3/25/2014
Current limiting circuit	8,648,661	2/11/2014
Linear multi-mode power amplifier for dynamic supply operation	8,598,951	12/3/2013
Tunable directional power combiner	8,508,296	8/13/2013
Direct DC coupled push-pull BJT driver for power amplifier with built-in gain and bias current signal dependent expansion	8,497,736	7/30/2013
Wideband RF power amplifier for multi-mode multi-band applications	8,461,931	6/11/2013
Power control circuit for radio frequency power amplifiers	8,432,228	4/30/2013
Power amplifier protection circuit	8,258,876	9/4/2012
Multi-stage power amplifier with enhanced efficiency	8,130,043	3/6/2012
Timing functions to optimize code-execution time	7,890,288	2/15/2011
Temperature compensated power detector	7,890,065	2/15/2011
High-power switch	7,852,172	12/14/2010
System and method for frequency multiplexing in double-conversion receivers	7,830,456	11/9/2010
Tuning circuitry utilizing frequency translation of an impedance from a fixed-filter frequency response	7,764,942	7/27/2010
Structures and methods for fabricating vertically integrated HBT-FET device	7,718,486	5/18/2010

Tunable balanced loss compensation in an electronic filter	7,639,069	12/29/2009
Electrostatic discharge protection device	7,586,720	9/8/2009
Voltage regulated power supply system	7,564,230	7/21/2009
Device and method for power amplifier noise reduction	7,545,218	6/9/2009
System and method for improving power efficiency in GSM power amplifiers	7,545,217	6/9/2009
System and method for distortion cancellation in amplifiers	7,459,974	12/2/2008
CDMA power amplifier design for low and high power modes	7,443,236	10/28/2008
Method and system for image rejection by using post mixer I/Q equalization	7,400,873	7/15/2008
Power amplifier having curve-fitting predistorter	7,385,447	6/10/2008
Device and method for power amplifier noise reduction	7,348,852	3/25/2008
System and method for distortion cancellation in amplifiers	7,301,396	11/27/2007
Variable gain amplifier	7,292,104	11/6/2007
Multi-mode digital bias control for enhancing power amplifier efficiency	7,248,111	7/24/2007
CDMA power amplifier design for low and high power modes	7,202,736	4/10/2007
Method and apparatus for gain control	7,173,406	216/2007
Method and apparatus for compensating and improving efficiency in a variable power amplifier	7,102,444	9/5/2006
Electrostatic discharge protection device	7,071,514	7/4/2006
Temperature compensated bias network	7,019,508	3/28/2006
Structures and methods for fabricating vertically integrated HBT/FET device	7,015,519	3/21/2006
Method and apparatus for optimization of amplifier with adjustable output range	7,009,454	3/7/2006
Monolithically fabricated HBT amplification stage with current limiting FET	6,998,920	2/14/2006
Efficiency enhancement for MMIC amplifiers	6,970,039	11/29/2005
Low bias current/temperature compensation current mirror for linear power amplifier	6,937,102	8/30/2005
Bias circuit linearization and dynamic power control	6,882,227	4/19/2005
Compact layout for a semiconductor device	6,856,004	2/15/2005

Transient overvoltage protection circuit	6,853,526	2/8/2005
Gain block with stable internal bias from low-voltage power supply	6,842,075	1/11/2005
Power amplifier with load switching circuit	6,806,767	10/19/2004
Dynamic matching in cascade circuits	6,803,824	10/12/2004
Treatment Agent for Hydrophilicity and Method for Preparing Thereof	6,790,900	9/14/2004
Integrated circuits with scalable design	6,760,900	7/6/2004
High directivity multi-band coupled-line coupler for RF power amplifiers	6,759,922	7/6/2004
Multi-mode amplifier bias circuit	6,753,734	6/22/2004
Low stress thermal and electrical interconnects for heterojunction Bipolar transistors	6,724,067	4/20/2004
Portable tube holder apparatus	6,719,518	4/13/2004
Gain control circuit with well-defined gain states	6,710,657	3/23/2004
Laser-trimmable digital resistor	6,664,500	12/16/2003
Linearity Radio Frequency Switche with Low Control Voltage	6,642,578	11/4/2003
System and method for prototyping and fabricating complex microwave circuits	6,645,790	11/11/2003
Amplifier bias adjustment circuit to maintain high-output third-order intermodulation distortion performance	6,639,466	10/28/2003
Active clamping circuit for power amplifiers	6,580,321	6/17/2003
Active power splitter with impedance matching	6,577,198	6/10/2003
Low bias current/temperature compensation current mirror for linear	6,559,722	5/6/2003
Wafer demount receptacle for separation of thinned wafer from mounting carrier	6,554,949	4/29/2003
Bias circuit for use with low-voltage power supply	6,515,546	2/4/2003
Multi-band amplifier	6,501,331	12/31/2002
Wafer demount receptacle for separation of thinned wafer from mounting carrier	6,491,083	12/10/2002
Wafer demount gas distribution tool	6,470,946	10/29/2002
GaAs MESFET having LDD and non-uniform P-well doping profiles	6,458,640	10/1/2002
Electrical contactor for automatic testing of chips including RF chips	6,437,585	8/20/2002

Spatula for separation of thinned wafer from mounting carrier	6,415,843	7/9/2002
Amplifier bias adjustment circuit to maintain high-output third-order intermodulation distortion performance	6,404,284	6/11/2002
Adjustable low spurious signal DC-DC converter	6,314,008	11/6/2001
Multiple-band amplifier	6,242,986	6/5/2001
Amplifier using a single polarity power supply	6,005,375	12/21/1999
Amplifier using a single polarity power supply	5,952,860	9/14/1999
Amplifier using a single polarity power supply and including depletion mode PET and negative voltage generator	5,892,400	4/6/1999
Multiple-band amplifier	5,774,017	6/30/1998
Multi-frequency local oscillators	5,748,049	5/5/1998
Method and apparatus for providing grounding to microwave circuit by low impedance means	5,736,913	4/7/1998
Automatic gain-control transimpedance amplifier	5,646,573	7/8/1997

<u>U.S. PENDING PATENT APPLICATIONS</u>		
TITLE	App. No.	App. Date
VCSEL ARRAY	14/495,643	9/24/2014
WIDE-BAND AMPLIFIERS USING CLIPPER CIRCUITS FOR REDUCED HARMONICS	14/276,400	5/13/2014
DOHERTY POWER AMPLIFIER WITH INTEGRATED PREDISTORTION	14/292,241	5/30/2014
DYNAMICALLY CONFIGURABLE BIAS CIRCUIT FOR CONTROLLING GAIN EXPANSION OF MULTI-MODE SINGLE CHAIN LINEAR POWER AMPLIFIERS	14/456,975	8/11/2014
CIRCUIT ARRANGEMENT FOR COMPENSATING CURRENT VARIATIONS IN CURRENT MIRROR CIRCUIT	13/789,908	3/8/2013
PROTECTION CIRCUIT	13/910,802	6/5/2013
SWITCHED INDUCTOR DC-DC CONVERTER	13/286,660	11/1/2011
SELF ESD PROTECTED DEVICE AND METHOD THEREOF	13/459,621	4/30/2012
INTEGRATED OUTPUT COMBINED FOR AMPLIFIER SYSTEM	13/548,774	7/13/2012
BOOST-BUCK DC-DC CONVERTER	13/624,339	9/21/2012
COMPACT DOHERTY COMBINER	13/713,409	12/13/2012
DOHERTY AMPLIFIER	13/710,765	12/11/2012
RADIO FREQUENCY (RF) COUPLERS	14/026,461	9/13/2013
REDUCTION OR DEFLAMINATION AND/OR DEVICE LIFT IN SEMICONDUCTOR PACKAGING	61/918,750	12/20/2013
PROGRAMMABLE BROAD BANDWIDTH GAIN AMPLIFIER	61/895,868	10/25/2013

SCHEDULE B

TRADEMARKS

TITLE	REG. NO.	ISSUE DATE
Anadigics logo – Korea	40-0621551-0000	6/16/05
Anadigics logo – United Kingdom	UK00002259306	6/29/01
Anadigics logo – Israel	146,149	9/3/02
Anadigics logo – Japan	4,773,176	5/21/04
Anadigics logo – Taiwan	01110808	7/16/04
Anadigics logo	2,896,625	10/26/04

SCHEDULE C

COPYRIGHTS/MASK WORKS

Copyright Number	Registration Date	Exploitation Date	Full Title/Description
MW0000018366	2007-10-05	18Sep06	C1051A_A (C9AGCS2B_E) single chip digital tuner / 4 semiconductor chips in housings + 2 col. composite plots
MW0000018716	2009-06-26	6Feb09	H6551A_A (99K00700_E) Wilan power amplifier / 4 semiconductor chips in housings + 2 col. composite plots
MW0000018777	2009-08-03	5May09	H6605A_A (H6224A_I) WCDMA/HSPA power amplifier / 4 semiconductor chips in housings + 2 col. composite plots
MW0000018962	2009-12-10	1Dec09	H9966A_A (FE9266AB_A) Wlan dual band TX/RX FEIC / 4 semiconductor chips in housings + 2 col. composite plots
MW0000018824	2009-10/20	13Aug09	H9970B_E (FA280_Q) dual band WiMax power amplifier, 2.3-2.7 GHz / semiconductor chips + col. composite plot
MW0000018731	2009-05-12	26Nov07	M1023B_A (USPT11D_E) GaAs upconverter for 1GHz integrated tuner product A1T1032/4 semiconductor chips + 2 col. composite plots
MW0000018797	2009-06-26	13Jul07	M2017A_E (BPGA5BDH_C) GaAs amplifier for DOCSIS 3.0 programmable gain amplifier/ 4 semiconductor chips in housings + 2 col. composite plots
MW0000018966	2009-12-14	14Mar08	M3623A_B (3619DB_A) 1GHz three-way active power splitter optimized for MoCA enabled subscriber equipment / 4 semiconductor chips in housings + 2 col. composite plots
MW0000018730	2009-05-12	26Nov07	C1032A_A (C18TIGER9A_A) CMOS down-conver for 1 GHz integrated tuner product A1T1032 / 4 semiconductor chips in housings + 2 col. composite plots
MW0000019044	2009-12-14	11Jan08	C6155A_A (PC6155A_A) quad-band GSM/SPRS/edge power amplifier module with integrated power control / 4 semiconductor chips + 2 col. composite plots
MW0000019042	2009-12-14	15Nov09	C6157A_G (PC6159A_D) CMOS controller / 4 semiconductor chips + 2 col. composite plots
MW0000018963	2009-12-14	22Dec07	H0155A_C (IX75C_A) quad-band

Copyright Number	Registration Date	Exploitation Date	Full Title/Description
			GSM/SPRS/EDGE power module with integrated power control / 4 semiconductor chips in housings + 2 col. Composite plots
MW0000018842	2009-10-30	1Jul09	H6159A_A (1Z44B_A) LB die for AWE6169 polar PAM / 4 semiconductor chips + col. composite plot
MW0000018827	2009-09-16	7Nov07	H6224A_D (H6224A_B) help3 dual-band 900 MHz/IMT UMTS 3.4V HSPA linear power amplifier module / 4 semiconductor chips + col. composite plot
MW0000018829	2009-09-16	7Nov07	H6243B_D (H6243B_D) help3 1.7 GHz/UMTS 3.4V/28.5 dBm linear power amplifier module / 4 semiconductor chips + col. composite plot
MW0000018828	2009-09-16	28Sep07	H6261A_B (WIMAX6261A_B) 2.5-2.7 GHz mobile WiMAX power amplifier module / 4 semiconductor chips + col. composite plot
MW0000018806	2009-11-18	10Nov09	H6264B_B (K6264J_B) AWT6264 / 4 semiconductor chips + 2 col. composite plot
MW0000018830	2009-09-16	11Oct07	H6309A_E (KPH01F_C) help2 AWS/KPCS CDMA 3.4V/28 dBm linear power amplifier module / 4 semiconductor chips + col. composite plot
MW0000018967	2009-12-14	28Aug08	H6388A_C (C4507A_B) 450 MHz CDMA 3.4V/29.5dBm linear power amplifier module / 4 semiconductor chips in housings + 2 col. composite plots
MW0000018798	2009-06-26	6Jul07	H6423A_A (Y3V25B_D) WiMAX power amplifier / 4 semiconductor chips in housings + 2 col. composite plots
MW0000019081	2010-08-02	18Dec09	H9935B_E (KPXEG10_E) AWL9935 Kilmer Peak FEM B / 4 semiconductor chips + 2 col. composite plots
MW0000018964	2010-01-20	13May08	M2420A_B (CSDI00NGC_B) high output power doubler line amplifier / 4 semiconductor chips in housings + 2 col. composite plots
MW0000018965	2010-01-20	15Oct09	M2447A_A (2UESD2407_B) 2UM line amp / 4 semiconductor chips in housings + 2 col. composite plots
MW0000019043	2010-01-20	22Aug08	M3606A_C (AS IP5SKC_E) active power splitter / 4 semiconductor chips + 2 col. composite plots
MW0000019133	2010-09-29	12Apr10	M3625A_A (APS3625_A) / 4

Copyright Number	Registration Date	Exploitation Date	Full Title/Description
MW0000019130	2010-09-13	28Jul10	semiconductor chips+ 2 col. composite plots C6157A_L (PC6157A_L) CMOS controller /4 semiconductor chips+ 2 col. composite plots
MW0000019161	2010-09-13	25Jun10	H0157A_B (HB6157C_D) high band linear pam /4 semiconductor chips + 2 col. composite plots
MW0000019078	2010-08-02	15Jan10	H6283B_B (WMAX35D7_F) 3.5 GHz WiMax PA / 4 semiconductor chips + 2 col. composite plots
MW0000018940	2010-04-12	1Apr10	H6323A_B (C6323A_C) H0323A_B (P6323A_C) Help cell/PCS PA w/coupler /4 semiconductor chips in housings + 2 col. composite plots
MW0000019013	2010-04-08	29Aug09	H6433A_A (Y3V35G_B) 3.4-3.6 GHz mobile WiMax /4 semiconductor chips in housings + 2 col. composite plots
MW0000019148	2010-10-06	30Oct10	H6625A_A (B5402A_E) help4 cell /4 semiconductor chips + 2 col. composite plots
MW0000019149	2010-11-15	15Dec10	H6628A_C (B8402C_G) help4 EGSM. /4 semiconductor chips + 2 col. composite plots
MW0000018939	2010-04-22	20Apr10	H6701A_B (T27D_C) IMT/PCS HELP4PAM /4 semiconductor chips in housing+ 2 col. composite plots
MW0000019079	2010-08-25	23Aug10	H6713A_B (B13H405C_B) band 13 help 4 PA /4 semiconductor chips + 2 col. composite plots
MW0000019134	2010-10-16	25Sep10	H9270A_C (927007_B) intel2Ghz PA module /4 semiconductor chips + 2 col. composite plots
MW0000019041	1020-01-13	11Dec09	H9555A_A (PA5344BB_B) WiFi FEIC / 4 semiconductor chips + 2 col. composite plots
MW0000018951	2010-03-23	18Dec09	H9935B_C (KPXEG3_B) front end integrated circuit / 4 semiconductor chips in housings + 2 col. composite plots
MW0000019259	2011-07-21	25Apr11	H6740A_A (B40H400A_C) wireless HELP4 TD-LTE PAS / 4 semiconductor chips+ 2 col. composite plots
MW0000019165	2011-03-15	8Dec10	H7123A_A (K7123FS_D) infrastructure power amplifiers / 4 semiconductor chips + 2 col. composite plots
MW0000019166	2011-02-03	11Nov10	H7127A_A (H7127FS_D) infrastructure power amplifiers / 4 semiconductor chips + 2 col. composite plots

Copyright Number	Registration Date	Exploitation Date	Full Title/Description
MW0000019214	2011-04-22	19Jan11	H9565A_A (FE5041AA258_B) AWL9565 / 4 semiconductor chips + 2 col. composite plots
MW0000019213	2011-04-22	6Jul10	M2443A_A (LA27PP5N2_B) 2UM line amp / 4 semiconductor chips + 2 col. composite plots
MW0000019324	2011-08-12	----	M2444A_A (2444029_A) 2um Line Amplifier / 4 semiconductor chips in housings + col. composite plots
MW0000019235	2011-05-31	8Feb11	WH6631A_A (B01H310D_A) AWT6631 / 4 semiconductor chips + 2 col. composite plots
MW0000019322	2011-10-12	15Mar11	WH6632A_A (B02H314C_B) AWT6632 / 4 semiconductor chips + col. composite plots
MW0000019321	2011-10-12	15Mar11	WH6634A_A (B04H306C_B) AWT6634 / 4 semiconductor chips + col. composite plots
MW0000019164	2011-03-15	5Jan11	H0521A_C (P1521B_B) Gobi3k high band / 4 semiconductor chips + 2 col. composite plots
MW0000019232	2011-06-09	23Feb11	H1628A_B (B8402A_N) (Help4 UMTS900 band 8) / 4 semiconductor chips + 2 col. composite plots
MW0000019238	2011-05-20	3Mar11	H6125A_B (B5402A_Q) IMT/PCS HELP4 PAM / 4 semiconductor chips + 2 col. composite plots
MW0000019233	2011-06-10	7Jan11	H6268A_A (T6268J_A) +26 dBm 2.5-2.7 GHz WiMAX PA / 4 semiconductor chips + 2 col. composite plots
MW0000019163	2011-03-15	28Feb11	H6521A_D (C1521B_D) Gobi3k low band / 4 semiconductor chips + 2 col. composite plots
MW0000019176	2011-03-07	2Mar11	H6615A_B (15C2A_E)/H0615A_B (15P2A_F) help3E EGSM/IMT PA w/coupler / 4 semiconductor chips + 2 col. composite plots
MW0000019177	2011-03-07	2Mar11	H6618A_B (18E2A_B)/H0618A_B (1813A_B) help3E EGSM/IMT PA w/coupler / 4 semiconductor chips + 2 col. composite plots
MW0000019201	2011-04-22	18Mar11	H6701A_G (T28R_G) PCS help4 PA / 4 semiconductor chips + 2 col. composite plots
MW0000019241	2011-08-03	07May11	H6707A_B (H4B704HA) HELP4 UMT band 7 / 4 semiconductor chips + 2 col. composite plots
MW0000019203	2011-04-22	14Jan11	H6712A_A (B12H403B_D) ALT6714 / 4

Copyright Number	Registration Date	Exploitation Date	Full Title/Description
			semiconductor chips + 2 col. composite plots
MW0000019229	2011-04-22	14Jan11	H6714A_A (B13H400B_D) / 4 semiconductor chips+ 2 col. composite plots
MW0000019258	2011-07-21	20Apr11	H6738A_A (B38H400A_C) wireless HELPA TD-LTE PAS / 4 semiconductor chips + 2 col. composite plots
MW0000019352	2012-09-24	26Jul12	C6156A_I (PC6180A_E) Controller for ALT6181 MMPA / 5 semiconductor chips+ col. composite plots
MW0000019343	2012-08-14	19Jul12	H0526A_B (G5HB06D_B) highband die for GOBI 5k module / 4 semiconductor chips in housings + col. composite plots
MW0000019353	2012-09-24	26Jul12	H6181A_B (Alt6181PI_H) Alt6181 MMPA / 4 semiconductor chips in housing + col. composite plots
MW0000019350	2012-10-23	10ct12	H6340B_B (OJT05_H) HELP CDMA band class 0, 10 high efficiency power amplifier module / 5 semiconductor chips in housings + col composite plots.
MW0000019342	2012-08-14	18Jul12	H6526A_B (G5LB40A_B) lowband die for GOBI 5k module / 4 semiconductor chips in housings + col. composite plots
MW0000019346	2012-04-26	3Apr12	H6615A_E(15CA_G)IH0615A_E (15P2A_I) HELP3E Cell/PCS PA / 4 semiconductor chips in housings + col. composite plots
MW0000019344	2012-04-26	3Apr12	H6618A_D (18E2A_D)IH0618A_D (18I3A_D) HELP3E EGSM/IMTPA / 4 semiconductor chips in housings+ col. composite plots
MW0000019347	2012-05-09	...	M2445A_A (2444NP029J_A) 870 Mhz hyrid line amp / 4 semiconductor chips in housings + col composite plots
MW0000019351	2012-09-24	26Jul12	MMPA06A_A laminate type 15R / 4 semiconductor chips + col. composite plots
MW0000019355	2012-09-24	26Jul12	WHO181A_D (HX04F_I) MMPA / 5 semiconductor chips in housing + col. composite plots
MW0000019354	2012-09-24	26Jul12	WH6181A_C (L06WE_B) Alt6181 MMPA / 5 semiconductor chips in housing + col. composite plots
MW0000019442	2013-02-19	40ct12	H7223A_B (K7223_DS_MIR_B) dual die amp/ 4 semiconductor chips in housings +

Copyright Number	Registration Date	Exploitation Date	Full Title/Description
			col. plots
MW0000019434	2013-02-19	40ct12	H7223A_B (K7223DS_B) dual die amp / 4 semiconductor chips in housings+ col. plots
MW0000019446	2013-02-19	310ct12	H7227A_B (K7227_DS_MIR_B) dual die amp / 4 semiconductor chips in housings + col. plots /
MW0000019441	2013-02-19	310ct12	H7227A_B (K7227DS_B) dual die amp / 4 semiconductor chips in housings + col. plots
MW0000019438	2013-02-19	5Apr12	H7228A_A (K7228A4_A) dual die amp / 4 semiconductor chips in housings + col. plots
MW0000019440	2013-02-19	5Apr12	H7228A_A (K7228A4_MIR_A) dual die amp / 4 semiconductor chips in housings + col. plots
MW0000019452	2013-05-29	02Feb13	H7230A_A (JWMX35D7_MIR_H) / 4 semiconductor chips in housings +col. campsite plots
MW0000019451	2013-05-29	06Mar13	H9280B_A (FE2563DD_B) / 4 semiconductor chips+ col. composite plots
MW0000019450	2013-05-29	10Mar13	H9281A_A (FE2582CB_A) / 4 semiconductor chips+ col. composite plots
MW0000019453	2013-05-29	10Mar13	H9580B_A (WLANFEIC_A) / 4 semiconductor chips in housings +col. campsite plots
MW0000019439	2013-03-22	6Mar13	H9581B_D (FE5792DE1LL_A) 50Hz WLAN front end module. / 4 semiconductor chips in housings + col. plots.